### PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT2803749

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

#### **CONVEYING PARTY DATA**

Name	Execution Date
YUJI TAKEBAYASHI	03/13/2014
MASAKAZU SHIMADA	03/13/2014
ATSUSHI MORIKAWA	03/13/2014

#### **RECEIVING PARTY DATA**

Name:	Hitachi Kokusai Electric Inc.
Street Address:	14-1, Sotokanda 4-chome
Internal Address:	Chiyoda-ku
City:	Tokyo
State/Country:	JAPAN
Postal Code:	1018980

#### **PROPERTY NUMBERS Total: 1**

Property Type	Number
Application Number:	14162318

#### **CORRESPONDENCE DATA**

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Phone: 301-424-3640 Email: mail@usiplaw.com **Correspondent Name:** PATRICK J. FINNAN

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ATTORNEY DOCKET NUMBER:	1022.0038C	
NAME OF SUBMITTER:	PATRICK J. FINNAN	
SIGNATURE:	/Patrick J. Finnan/	
DATE SIGNED:	04/07/2014	
	This document serves as an Oath/Declaration (37 CFR 1.63).	

**Total Attachments: 2** 

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## COMBINED DECLARATION (37 CFR 1.63) AND ASSIGNMENT FOR UTILITY OR DESIGN APPLICATION

Title of invention

# SUBSTRATE PROCESSING APPARATUS, METHOD OF MANUFACTURING SEMICONDUCTOR DEVICE AND NON-TRANSITORY COMPUTER-READABLE RECORDING MEDIUM

#### DECLARATION

As a below named inventor, I hereby declare that:

This declaration is directed to the above-identified application for United States Letters Patent and further identified by the Attorney Docket Number provided above in the header of this document.

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims.

I acknowledge the duty to disclose to the Office all information known to me to be material to patentability as defined in 37 CFR §1.56.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

#### ASSIGNMENT

For good and valuable consideration, the undersigned inventor(s), hereinafter individually or collectively referred to as "Assignor";

Hereby sell, assign and transfer to Hitachi Kokusai Electric Inc., a corporation organized and existing under the laws of Japan, having its principal place of business at c/o Hitachi Kokusai Electric Inc., 14-1. Sotokanda 4-chome, Chiyoda-ku, Tokyo 1018980, Japan, hereinafter "Assignee", its successors, assigns and legal representatives, the entire right, title and interest in and for the United States and all foreign countries, in and to any and all improvements which are disclosed in the above-identified application for United States Letters Patent, and in and to said application and all divisional, continuing, substitute, renewal, reissue, and all other applications for Letters Patent which have been or shall be filed in the United States and all foreign countries on any of said improvements; and in and to all original and reissued patents which have been or shall be filed in the United States and all foreign countries on said improvements;

Agree that said Assignee may apply for and receive Letters Patent for said improvements in its own name; and that, when requested, without charge to but at the expense of said Assignee, its successors, assigns and legal representatives, to carry out in good faith the intent and purpose of this assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all said improvements; execute all rightful oaths, assignments, powers of attorney and other papers; communicate to said Assignee, its successors, assigns, and legal representatives, all facts known to the undersigned relating to said improvements and the history thereof; and generally do everything possible which said Assignee, its successors, assigns or legal representatives shall consider desirable for aiding in securing and maintaining proper patent protection for said improvements and for vesting title to said improvements and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns and legal representatives; and

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Covenant with said Assignee, its successors, assigns and legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.
LEGAL NAME OF JOINT INVENTOR
Inventor: Yuli, TAKEBAYASHI
Having an address at: <u>c/o Hitachi Kokusai Electric Inc., 1. Yasuuchi 2 –chome, Yatsuo-machi,</u>
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Signature: Yuji Takebayashi Date: March 13,2019
LEGAL NAME OF JOINT INVENTOR
inventor: <u>Masakazu, SHIMADA</u>
Having an address at: <u>c/o Hitachi Kokusai Electric Inc., 1. Yasuuchi 2 –chome, Yatsuo-machi.</u>
Toyama-shi, Toyama 9392393, Japan
Signature: < 3 Section Date: Narch 13 , 2014
LEGAL NAME OF JOINT INVENTOR
Inventor: Atsushi, MORIKAWA
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Toyama-shi, Toyama 9392393, Japan
Signature: Atsuck! Morl Kawa Date: March 13, 2019
Note: An application data sheet (PTO/SB/14 or equivalent), naming the entire inventive entity, either accompanies this form or was filed previously and thus is currently of record in the file.

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**RECORDED: 04/07/2014**